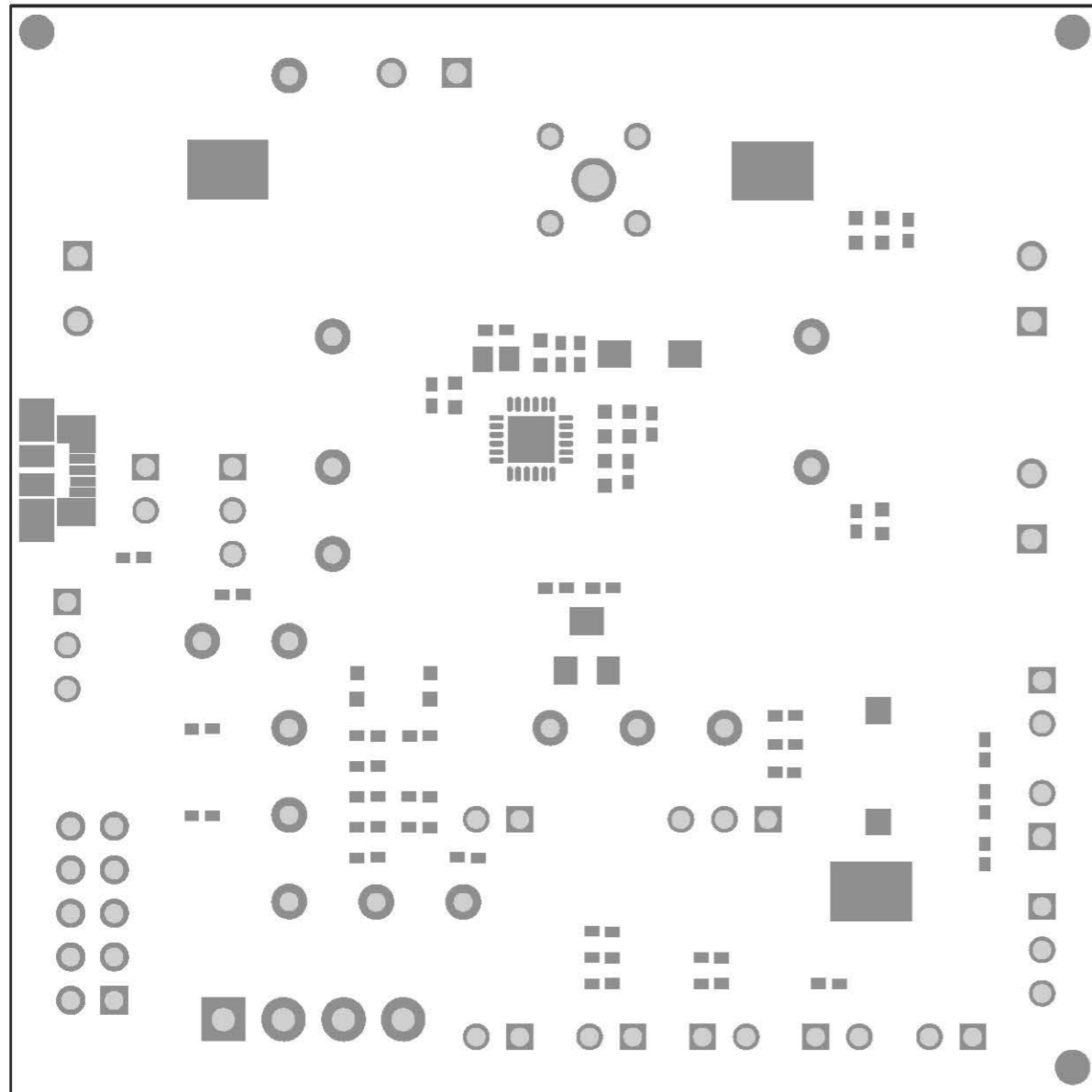
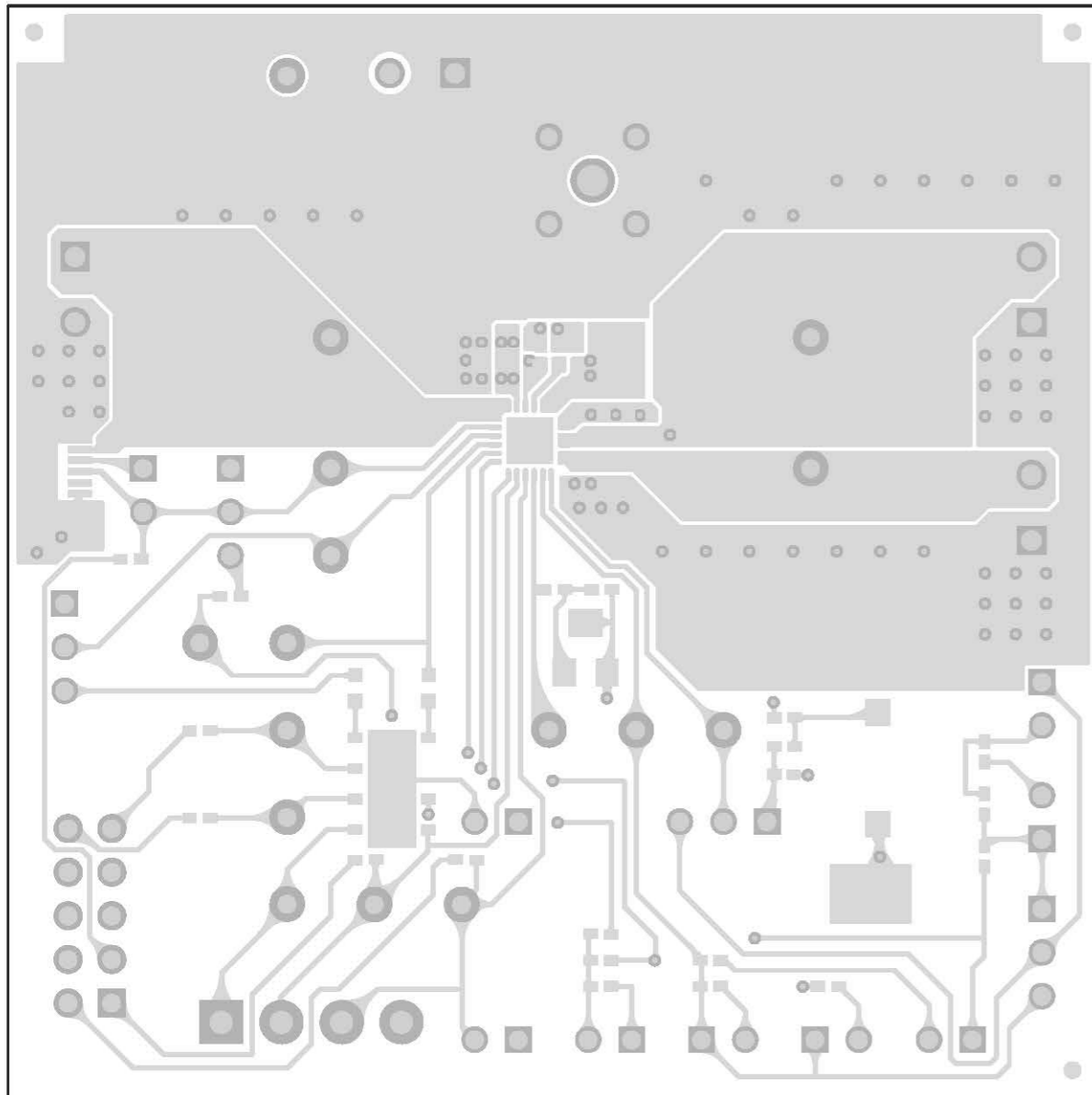


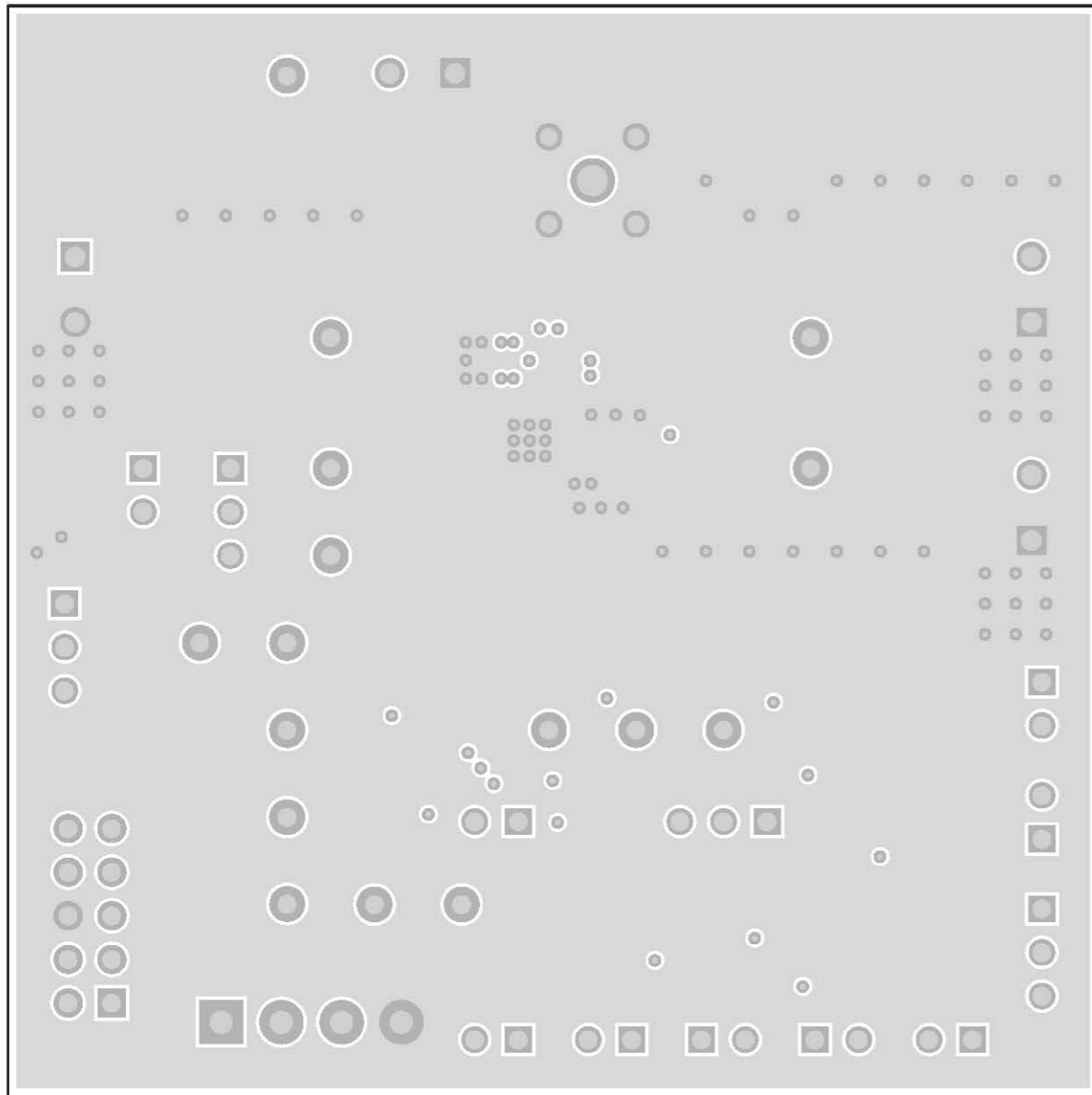
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = Top Overlay			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	



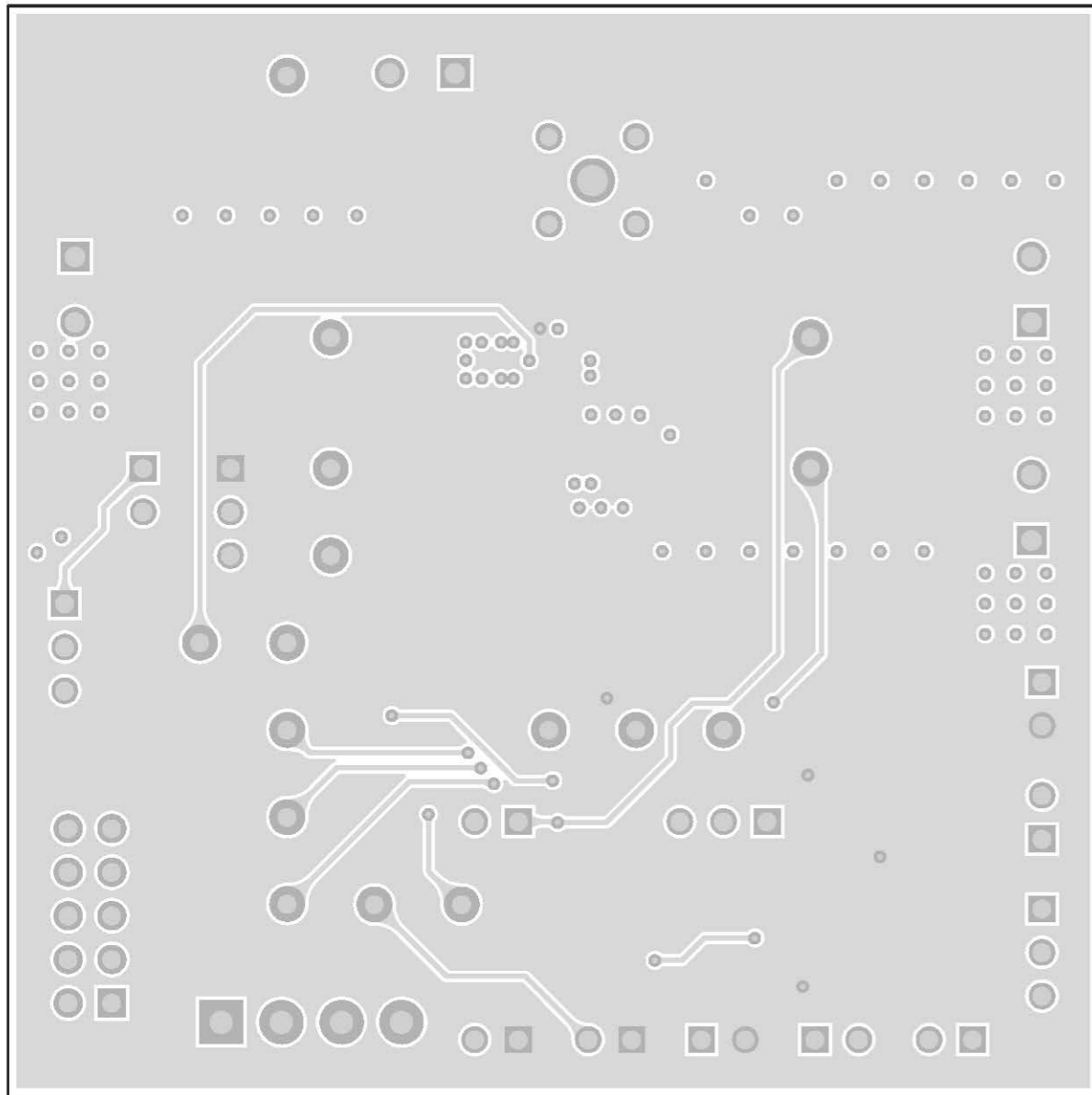
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = Top Solder			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	



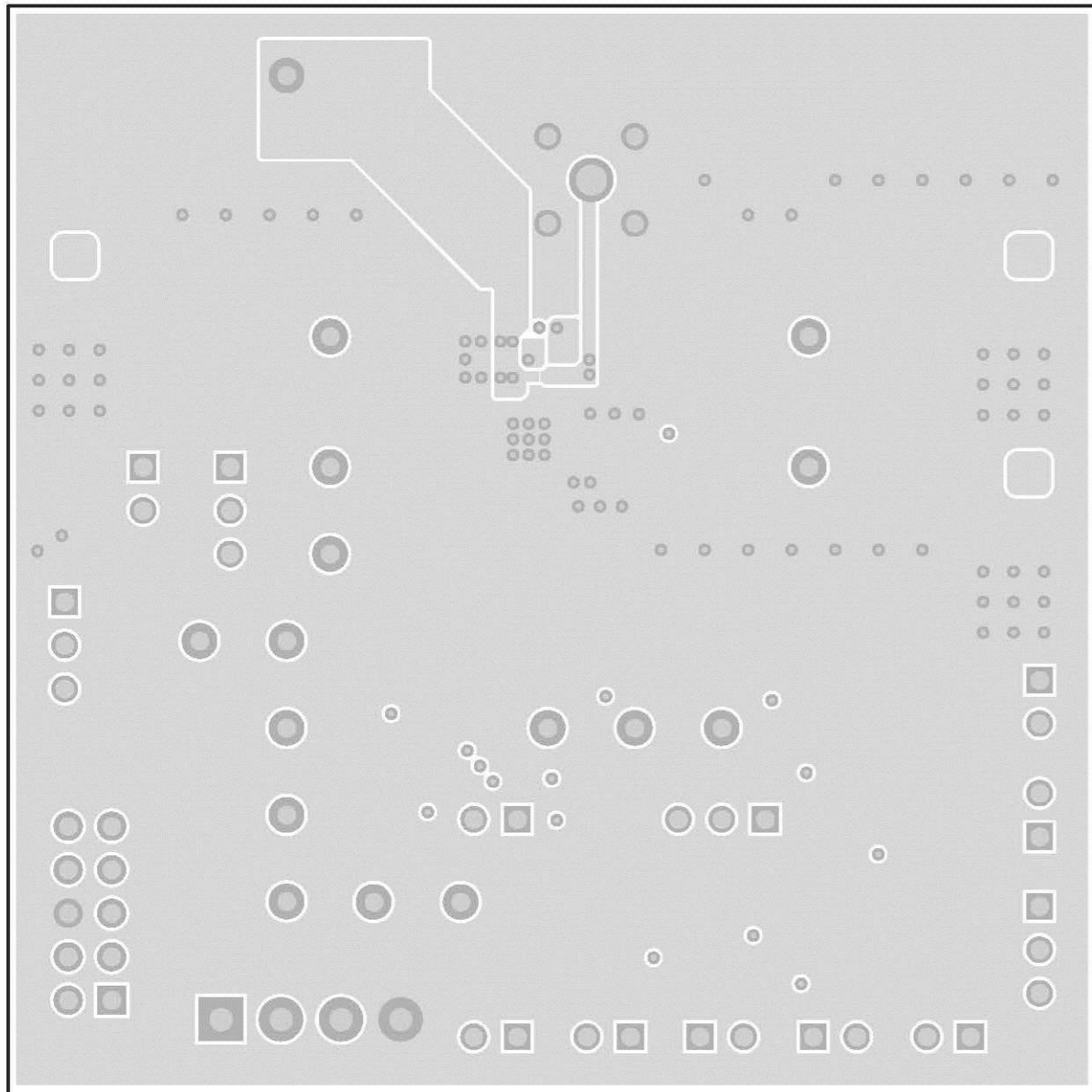
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = Top Layer			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = MidLayer1			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	

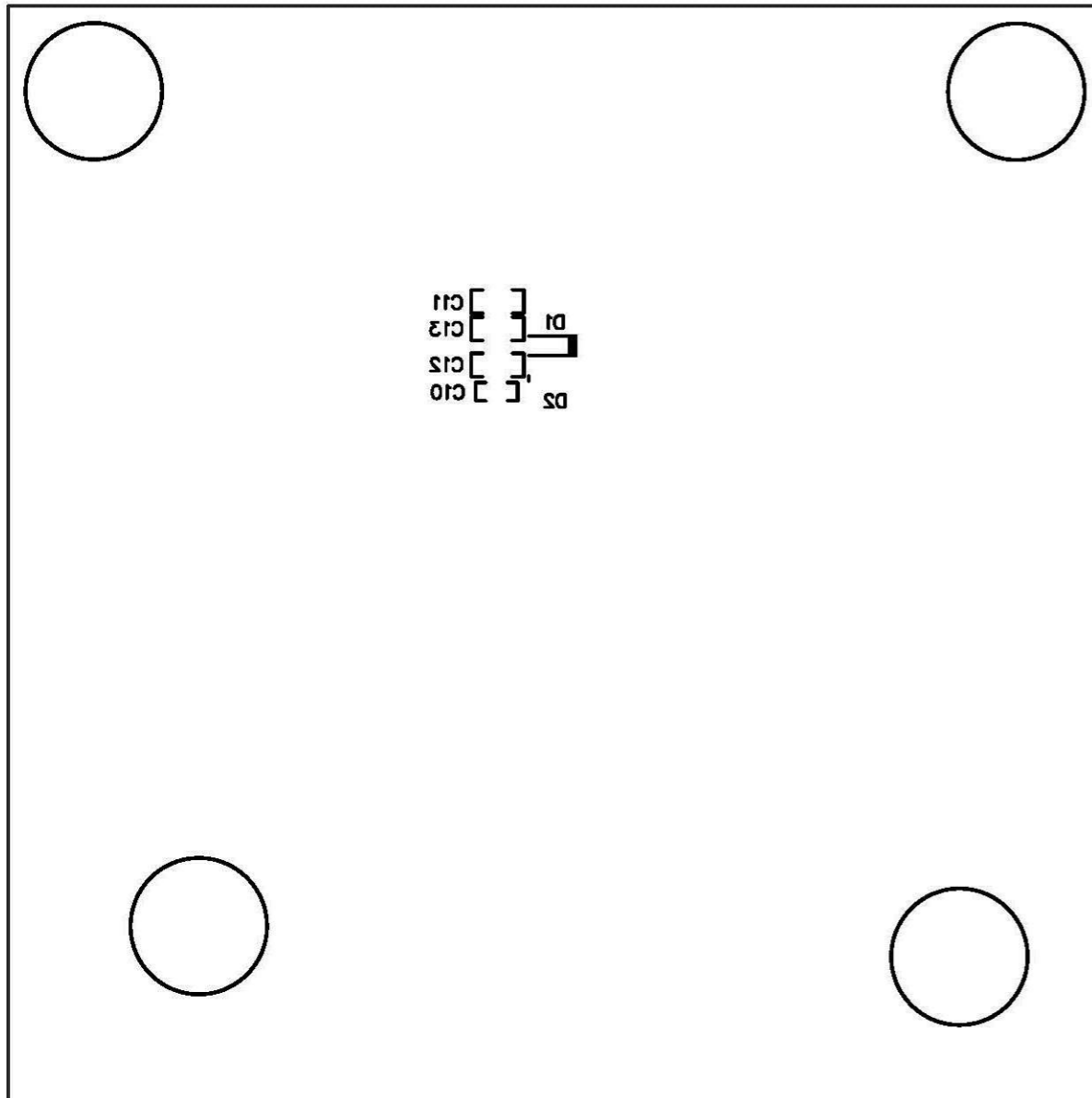


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = MidLayer2			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	



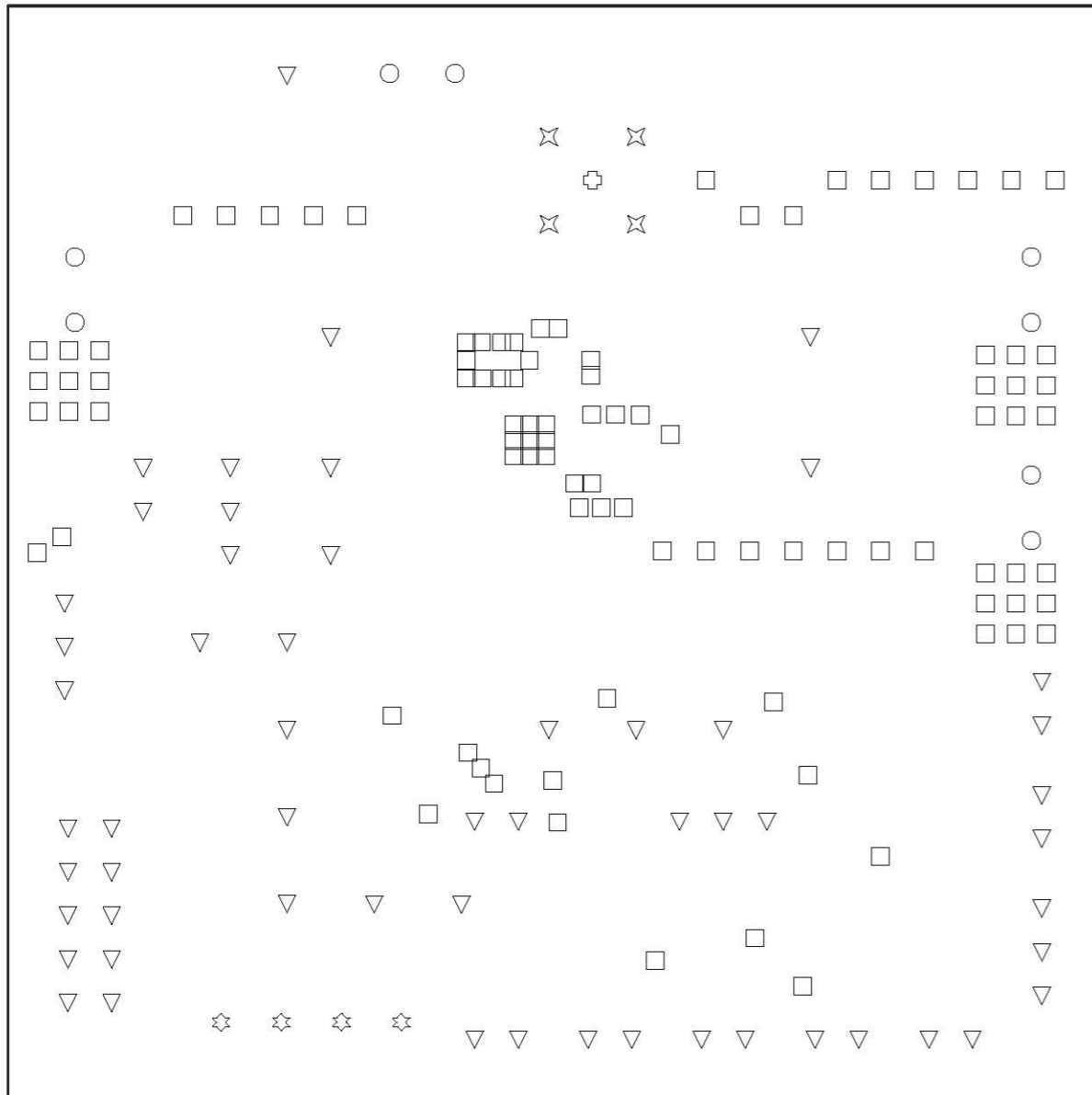
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = Bottom Layer			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	





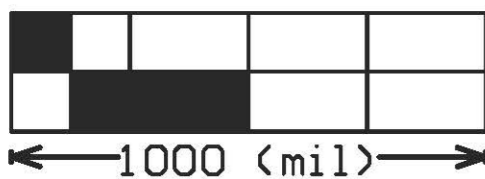
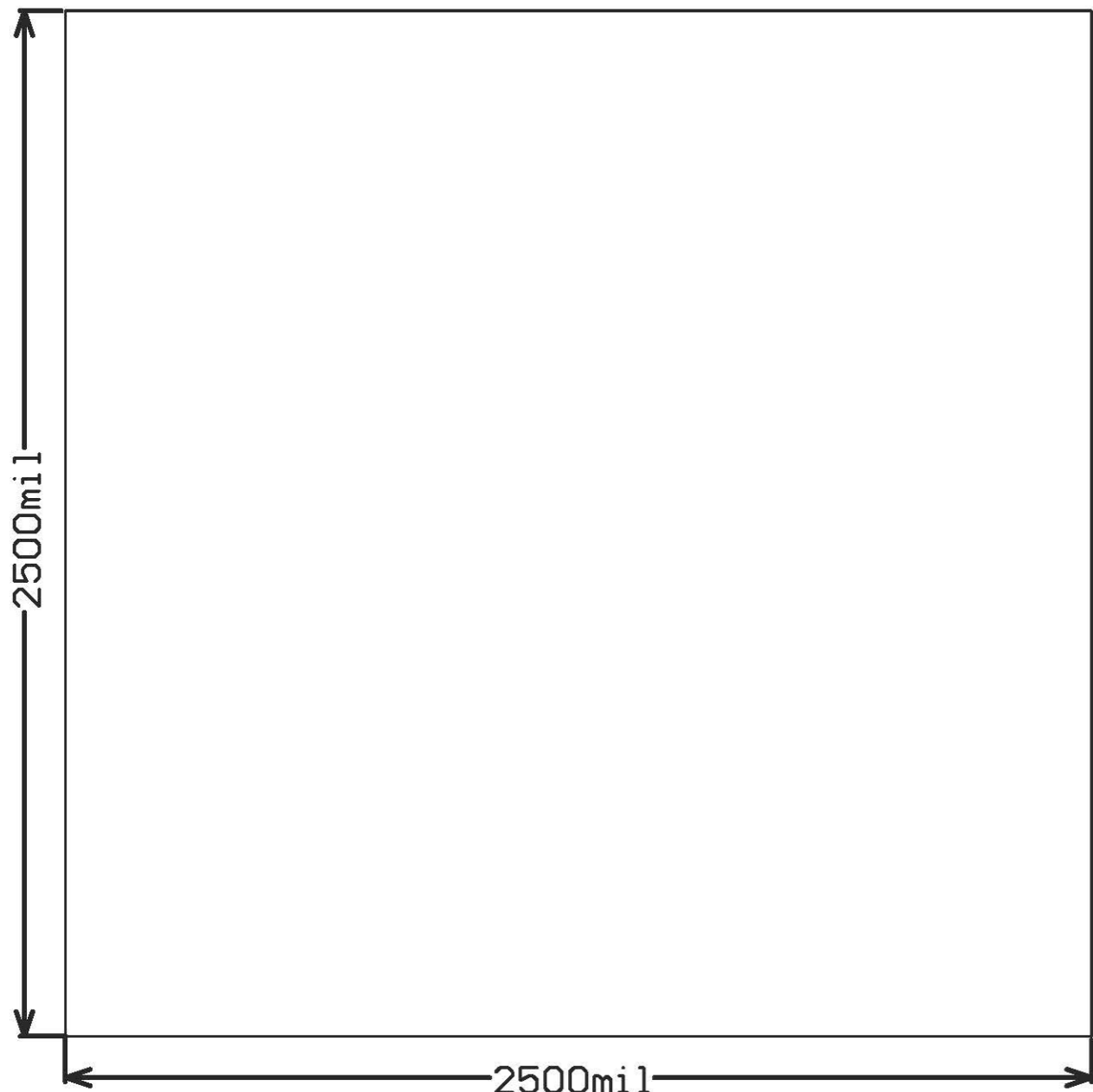
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = Bottom Overlay			
PLOT NAME =	GENERATED : 06/27/2014		TEXAS INSTRUMENTS





Legend is not interpreted until output  
Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = Drill Drawing			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR655	REV: A	SUN REV:
LAYER NAME = M2 Board Dimensions			
PLOT NAME =	GENERATED : 06/27/2014	TEXAS INSTRUMENTS	

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